

APPARATUS FOR AND METHOD OF CLEANING OBJECTS
TO BE PROCESSED
ABSTRACT OF DISCLOSURE

5 A cleaning apparatus and a cleaning method for re-
stricting an occurrence of water marks on a surface of a
object to be processed are provided. The cleaning apparatus
is constructed so as to dry wafers W, which have been
rinsed by DIW in a drying chamber 42, in a cooling system.
Thus, the reaction between, for example, IPA, DIW etc. and
silicon in surfaces of the wafers W is inactivated to cause
10 the surfaces to be oxidized with difficulty, so that it is
possible to restrict the occurrence of the water marks on
the surfaces.

(Fig. 4)